

Dual N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- Surface-mounted package
- Extremely low threshold voltage
- Advanced trench cell design

1.2 Applications

- Portable appliances
- Battery management

1.3 Quick reference

- $BV \geq 16\text{ V}$
- $R_{DS(ON)} \leq 22\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- $P_{tot} \leq 0.83\text{ W}$
- $R_{DS(ON)} \leq 33\text{ m}\Omega @ V_{GS} = 2.5\text{ V}$
- $I_D \leq 5\text{ A}$

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Source(S1)		
2	Drain(D1)		
3	Source(S2)		
4	Gate(G2)		
5	Drain(D2)		
6	Gate(G1)		

3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_A = 25\text{ }^\circ\text{C}$	-	16	V
V_{GS}	Gate-Source Voltage	$T_A = 25\text{ }^\circ\text{C}$	-	± 12	V
I_D^*	Drain Current	$T_A = 25\text{ }^\circ\text{C}, V_{GS} = 4.5\text{ V}$	-	5	A
$I_{DM}^{*,**}$	Pulsed Drain Current	$T_A = 25\text{ }^\circ\text{C}, V_{GS} = 4.5\text{ V}$	-	20	A
P_{tot}^*	Total Power Dissipation	$T_A = 25\text{ }^\circ\text{C}$	-	0.83	W
		$T_A = 100\text{ }^\circ\text{C}$	-	0.3	
T_{stg}	Storage Temperature		- 55	150	$^\circ\text{C}$
T_J	Junction Temperature		-	150	$^\circ\text{C}$
I_S^*	Diode Forward Current	$T_A = 25\text{ }^\circ\text{C}$	-	1	A
$R_{\theta JA}^*$	Thermal Resistance- Junction to Ambient		-	150 $^\circ\text{C}$	/ W

4. Marking Information

Product Name	Marking
8205S	8205S : Date Code

5. Ordering Code

8205 <input type="checkbox"/> Assembly Material	Assembly Material G: Halogen and Lead Free Device
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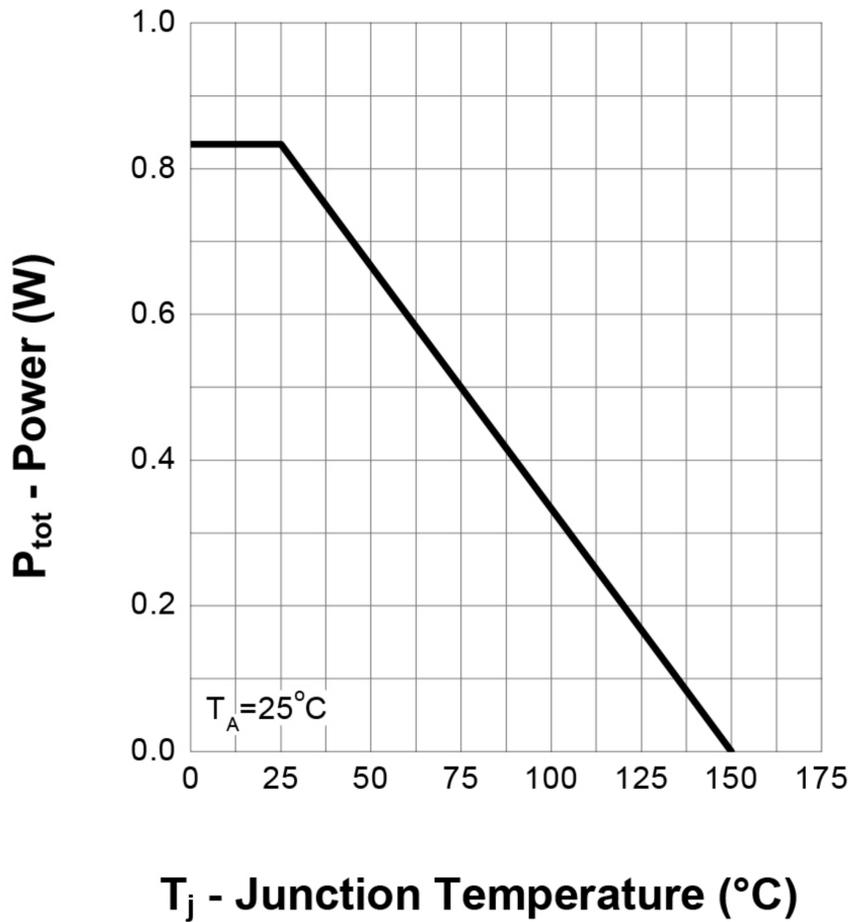
6. Electrical Characteristics (T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _{DS} = 250 μA	16	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = 250 μA	0.5	-	1.0	V
I _{DSS}	Drain Leakage Current	V _{DS} = 16 V, V _{GS} = 0 V	-	-	1	μA
		T _J = 85 °C	-	-	30	μA
I _{GSS}	Gate Leakage Current	V _{GS} = ± 10 V, V _{DS} = 0 V	-	-	± 100	nA
R _{DS(ON)} ^a	On-State Resistance	V _{GS} = 4.5 V, I _{DS} = 5 A	-	21	22	mΩ
		V _{GS} = 2.5 V, I _{DS} = 3 A	-	24	33	
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} = 1 A, V _{GS} = 0 V	-	-	1.3	V
Dynamic Characteristics^b						
C _{iss}	Input Capacitance	V _{GS} = 0 V, V _{DS} = 10 V Frequency = 1 MHz	-	417	-	pF
C _{oss}	Output Capacitance		-	90	-	
C _{rss}	Reverse Transfer Capacitance		-	74	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} = 10 V, V _{GEN} = 4.5 V, R _G = 6 Ω, R _L = 1.6 Ω, I _{DS} = 5 A	-	6	-	ns
t _r	Turn-on Rise Time		-	56	-	
t _{d(off)}	Turn-off Delay Time		-	23	-	
t _f	Turn-off Fall Time		-	13	-	
Gate Charge Characteristics^b						
Q _g	Total Gate Charge	V _{GS} = 4.5 V, V _{DS} = 10 V, I _{DS} = 5 A	-	6.7	-	nC
Q _{gs}	Gate-Source Charge		-	1.2	-	
Q _{gd}	Gate-Drain Charge		-	2	-	

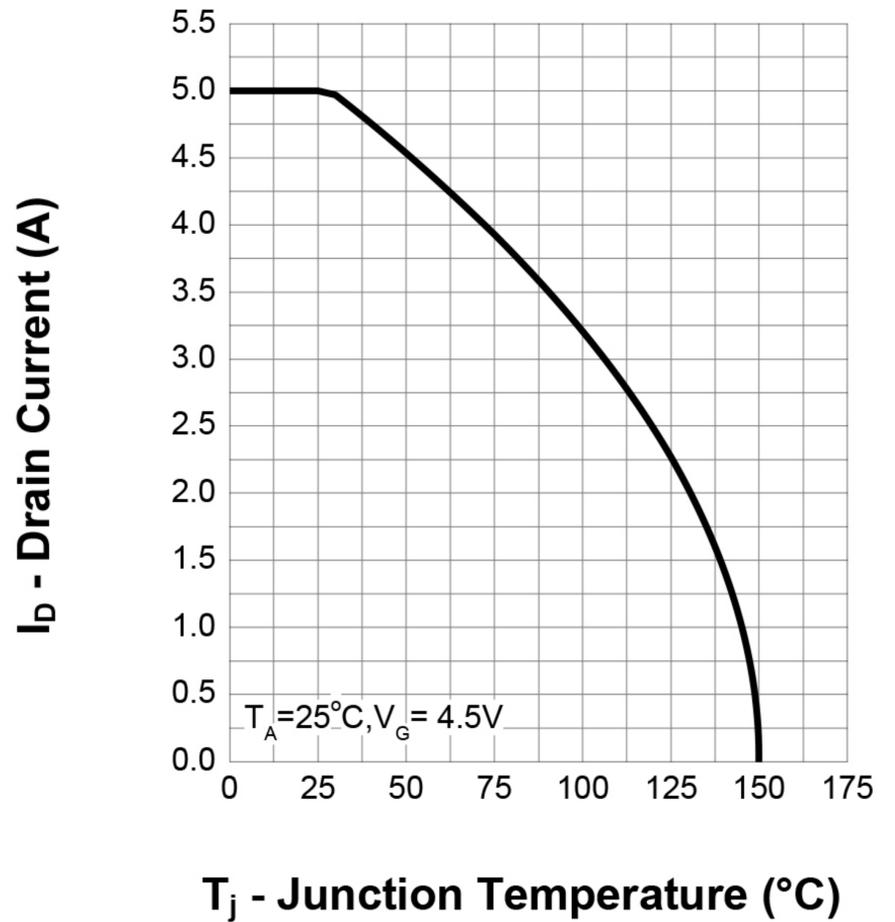
7. Typical Characteristics

N-channel:

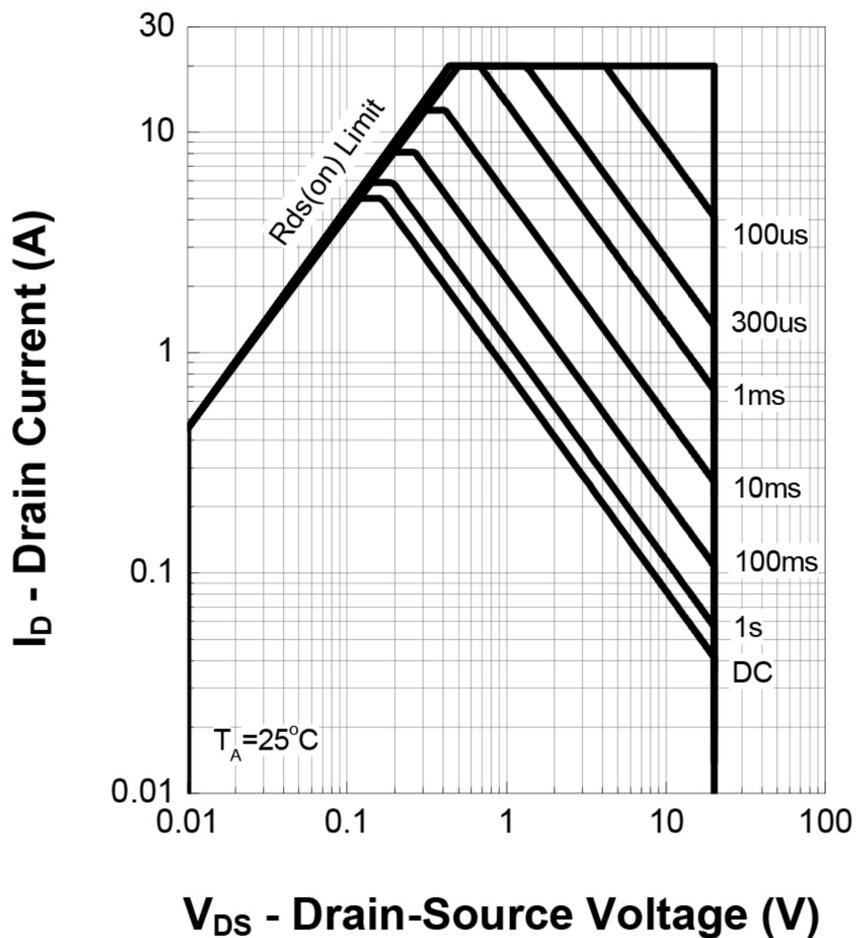
Power Capability



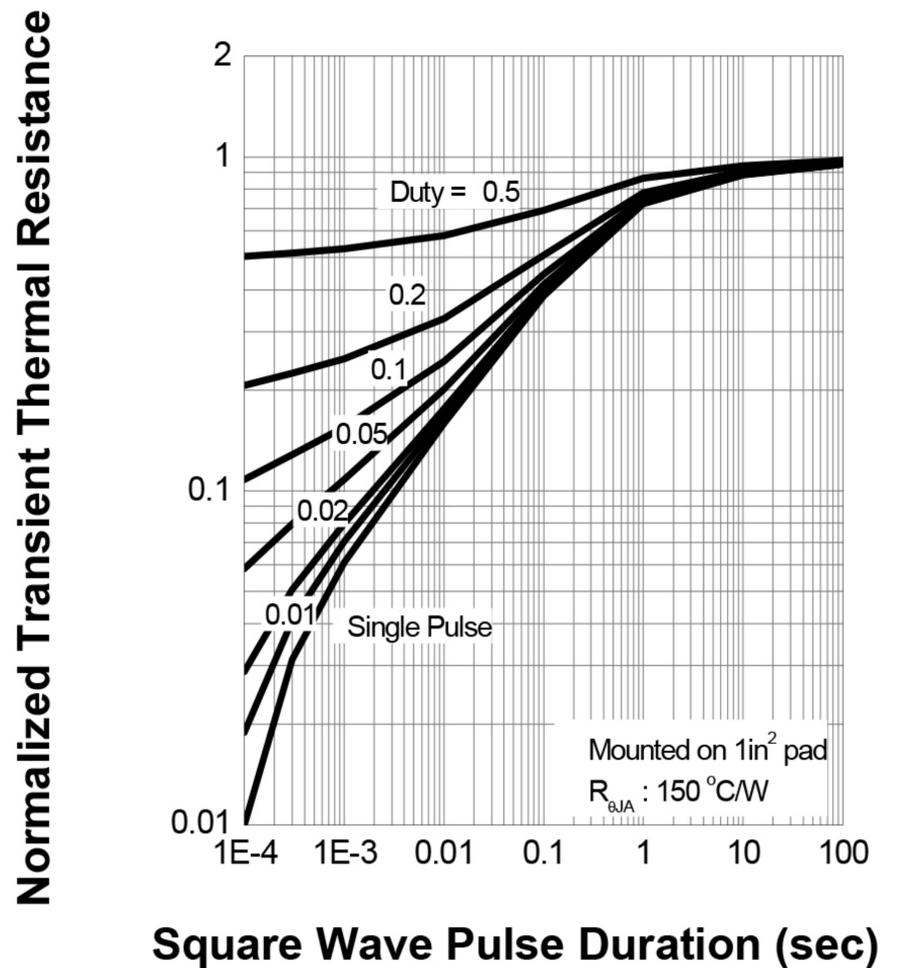
Current Capability



Safe Operation Area



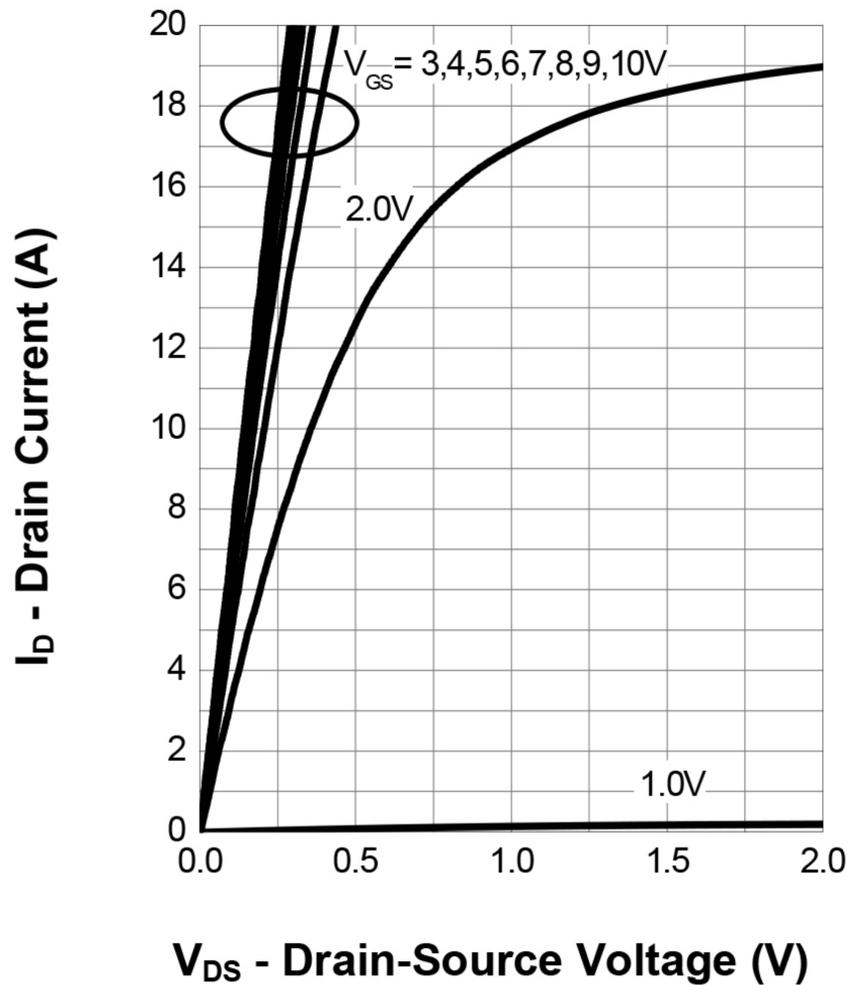
Transient Thermal Impedance



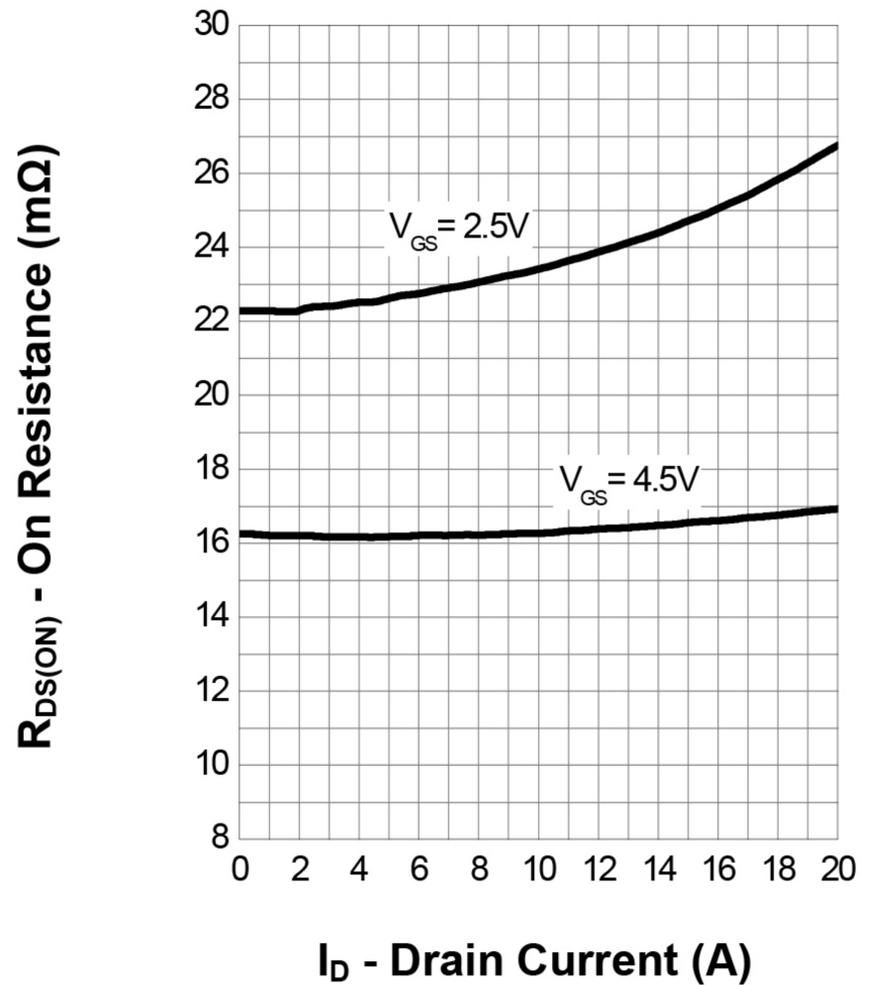
7. Typical Characteristics (cont.)

N-channel:

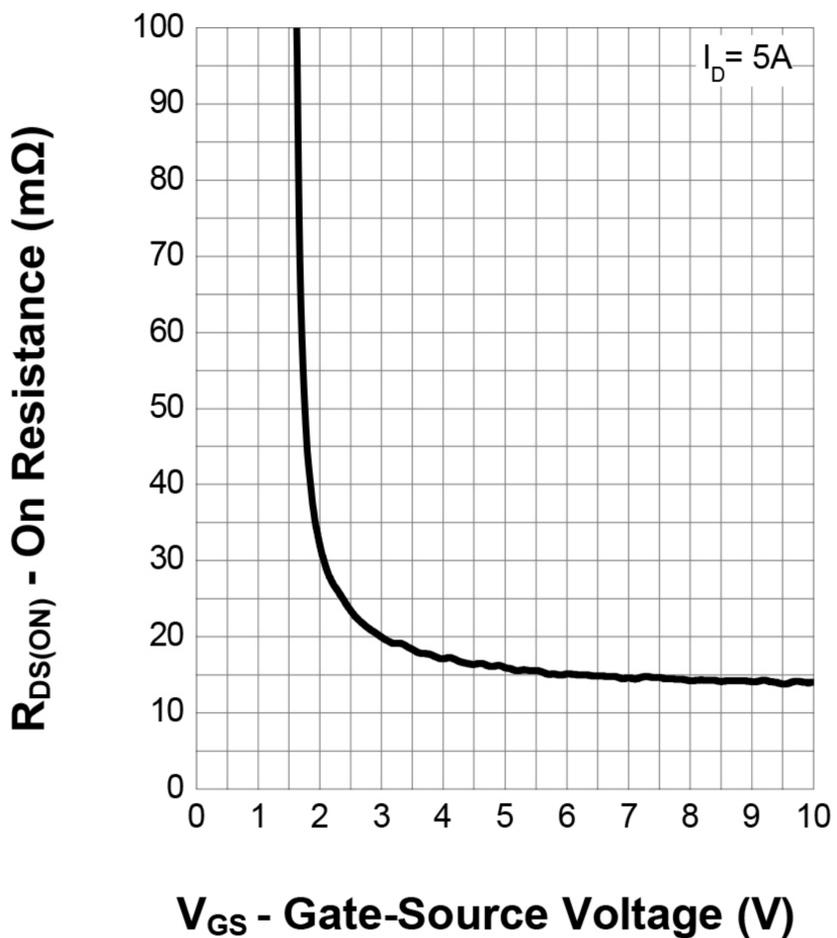
Output Characteristics



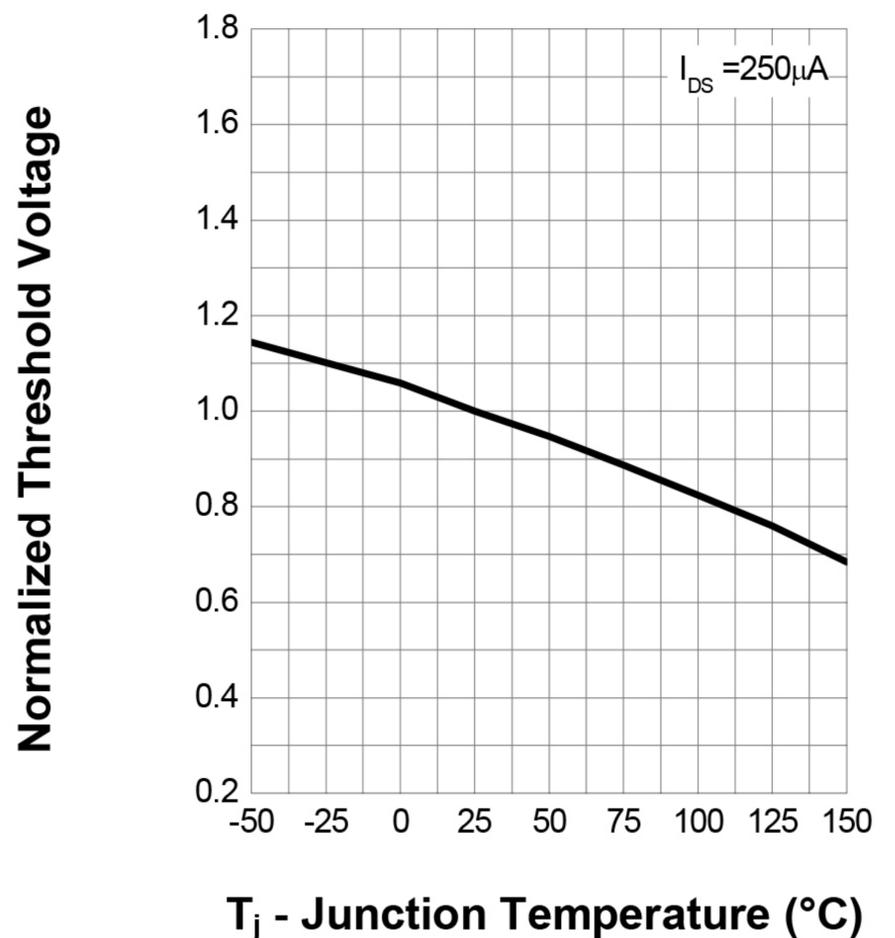
On Resistance



Transfer Characteristics



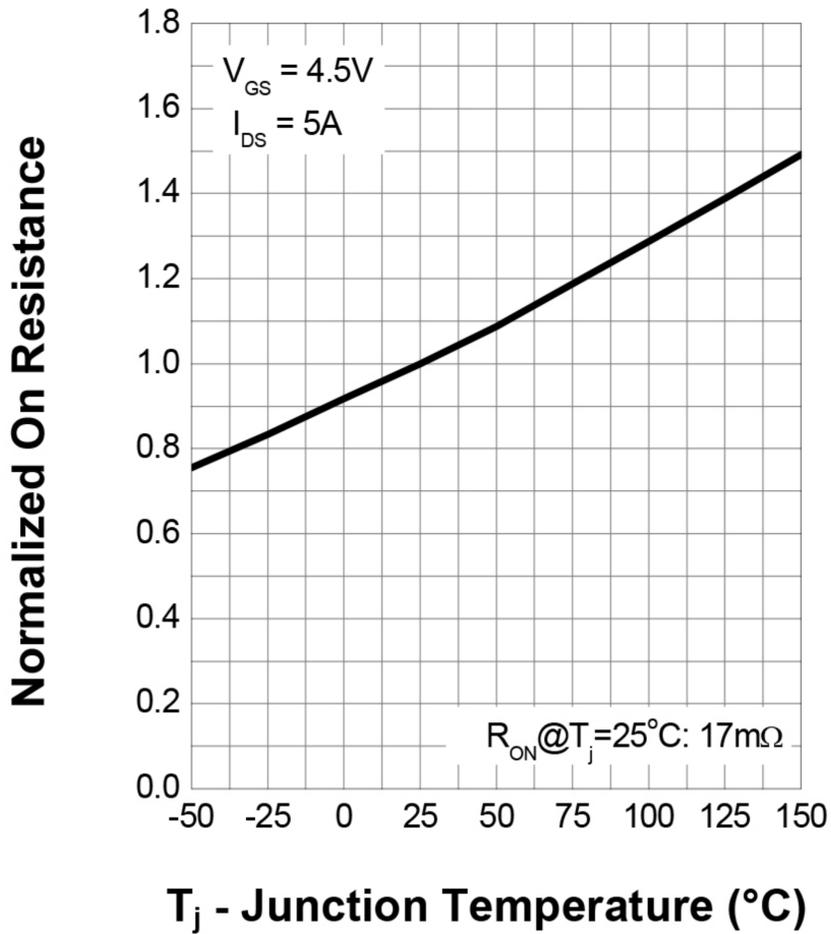
Normalized Threshold Voltage



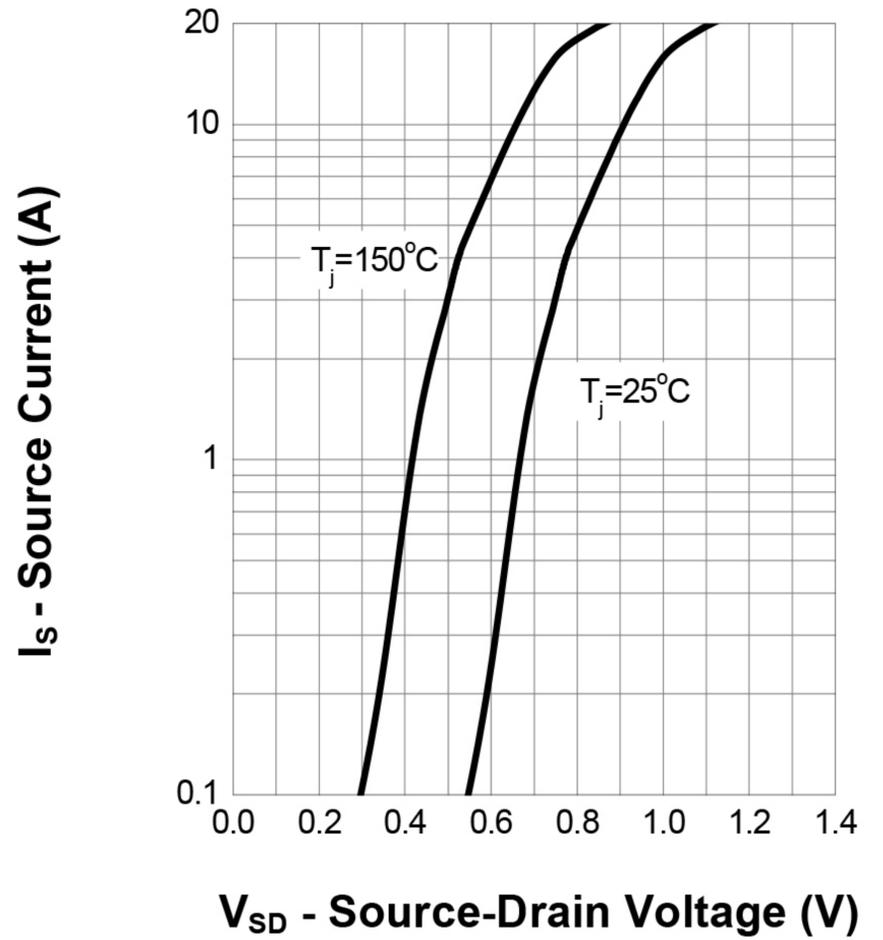
7. Typical Characteristics (cont.)

N-channel:

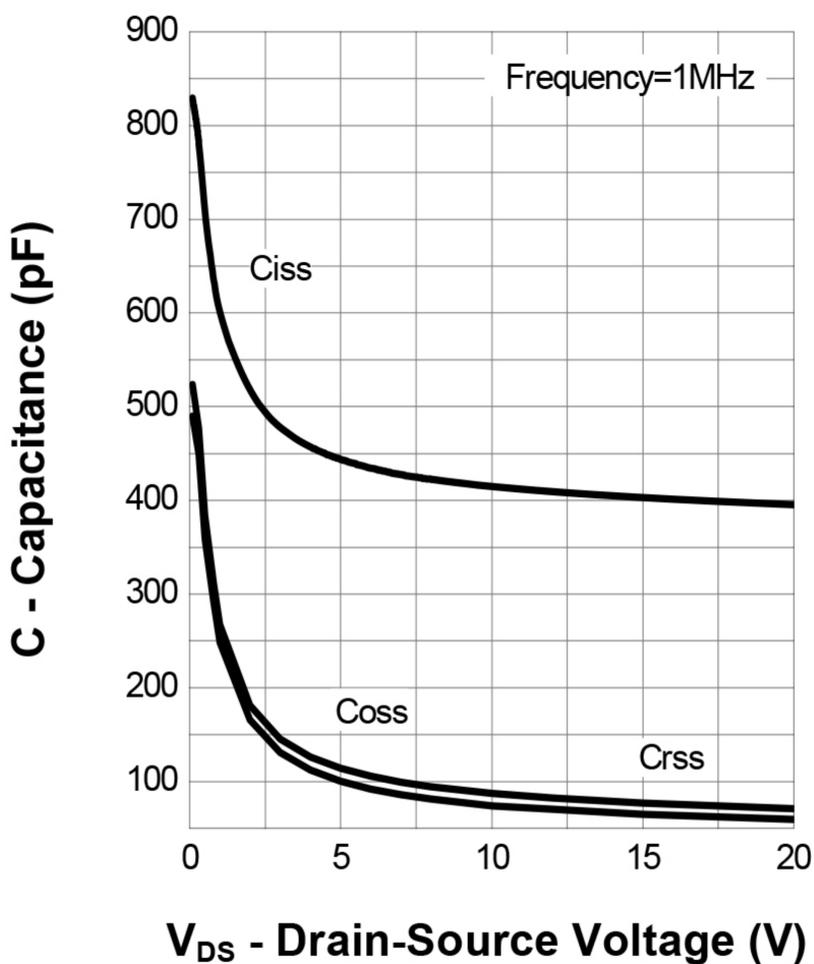
Normalized On Resistance



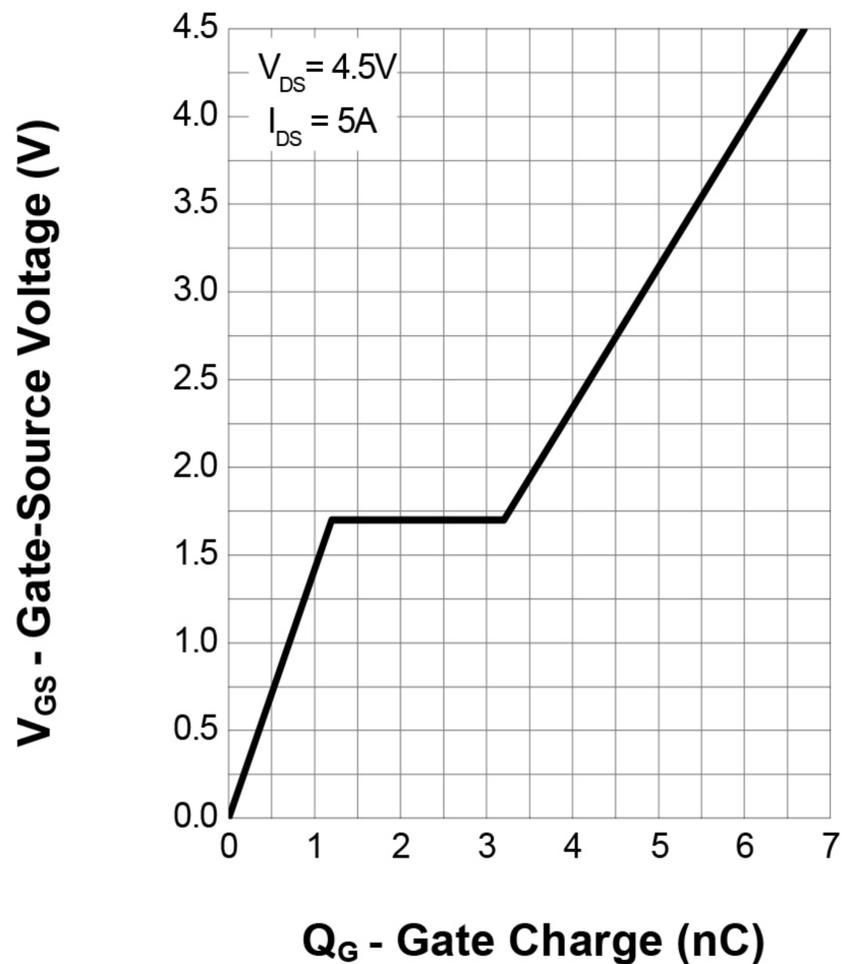
Diode Forward Current



Capacitance

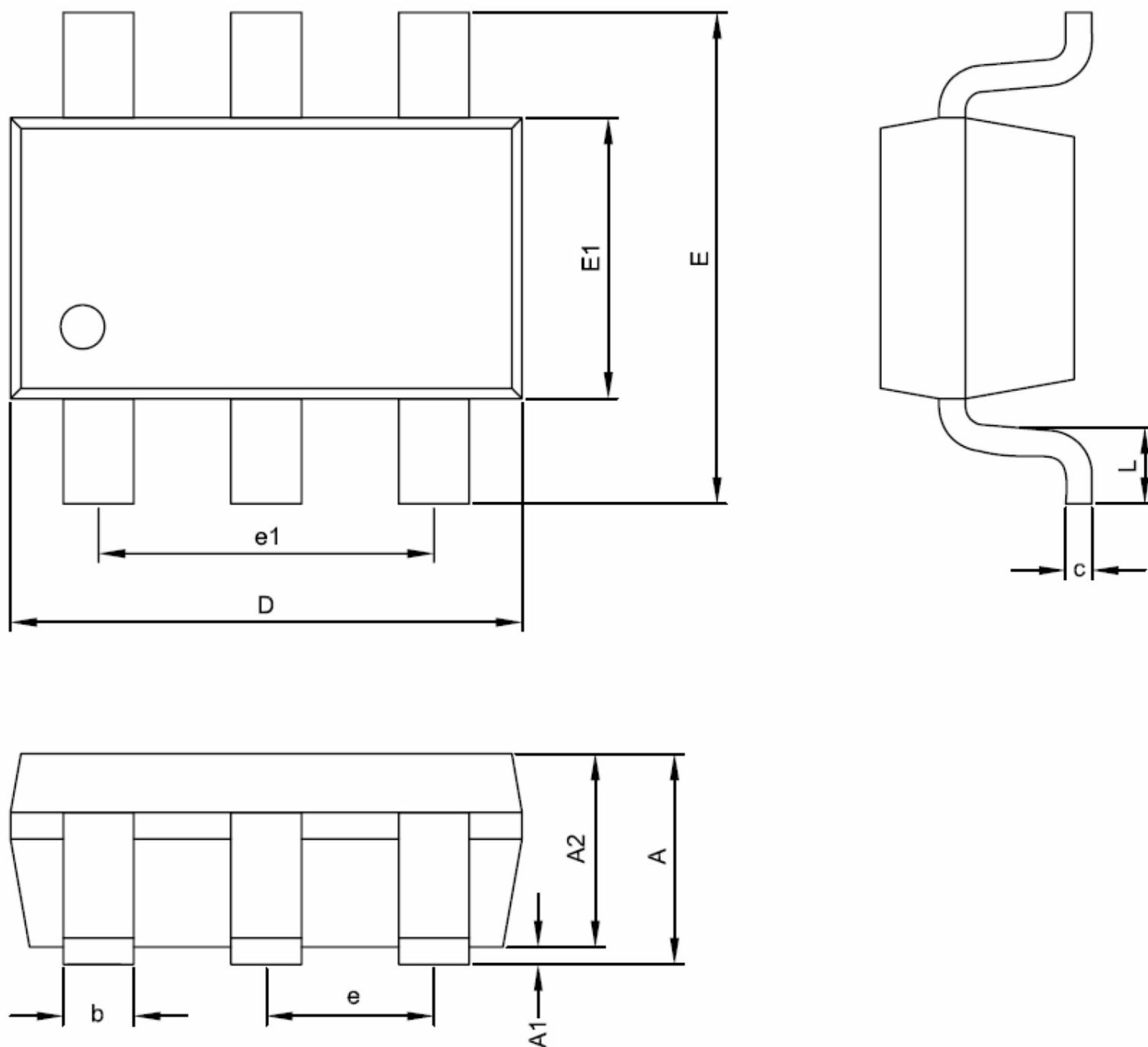


Gate Charge



8.Package Dimensions

TSOT23-6L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	—	0.90
A1	0.00	0.10
A2	0.70	0.80
D	2.90 BSC	
E	2.80 BSC	
E1	1.50	1.70
c	0.08	0.25
b	0.30	0.51
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60